
Pinout for 9 mm x 7mm BGA package



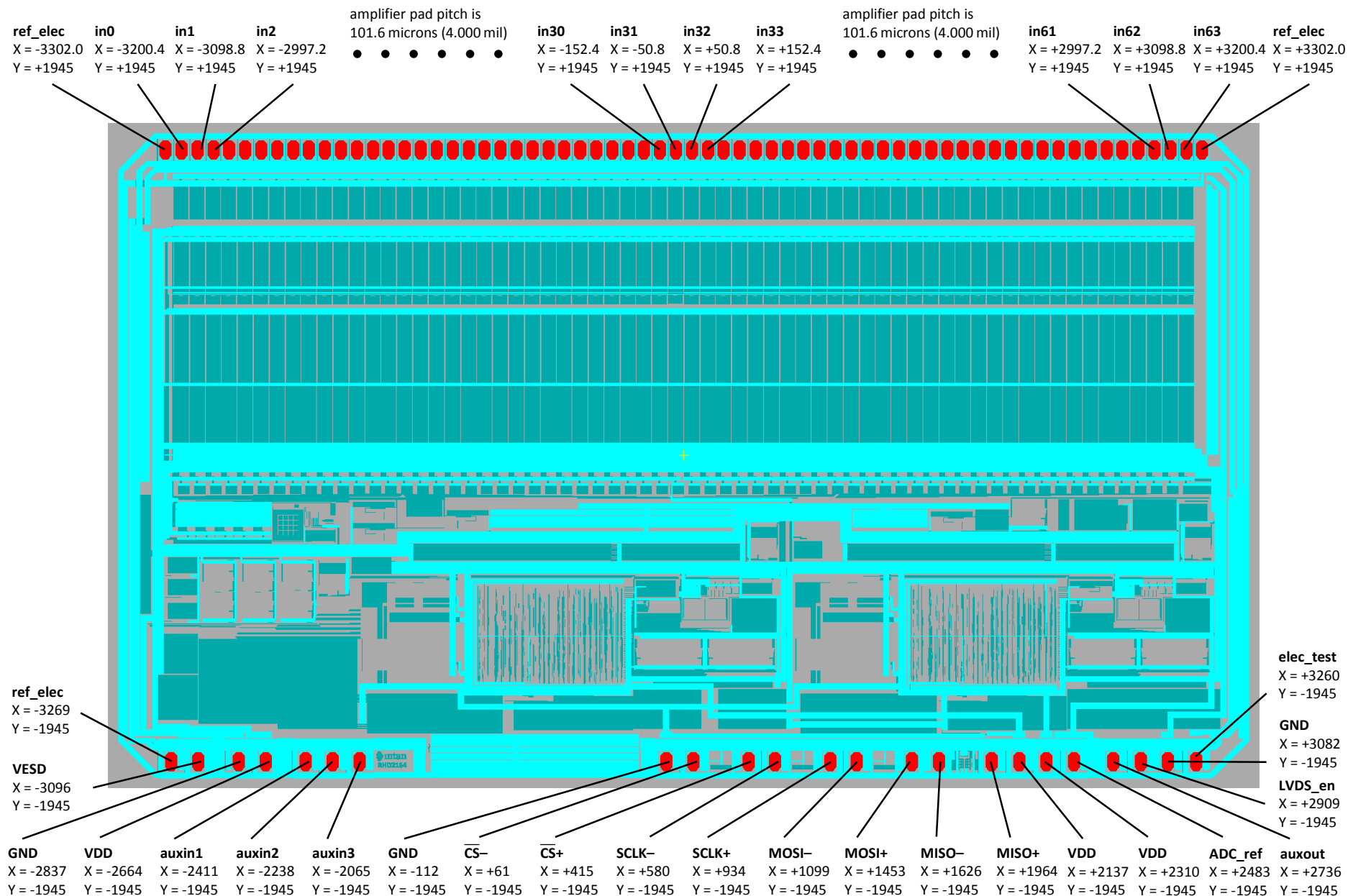
Reid R. Harrison

Intan Technologies

RHD2164

Coordinates of Bond Pad Centers, Relative to Center of Design

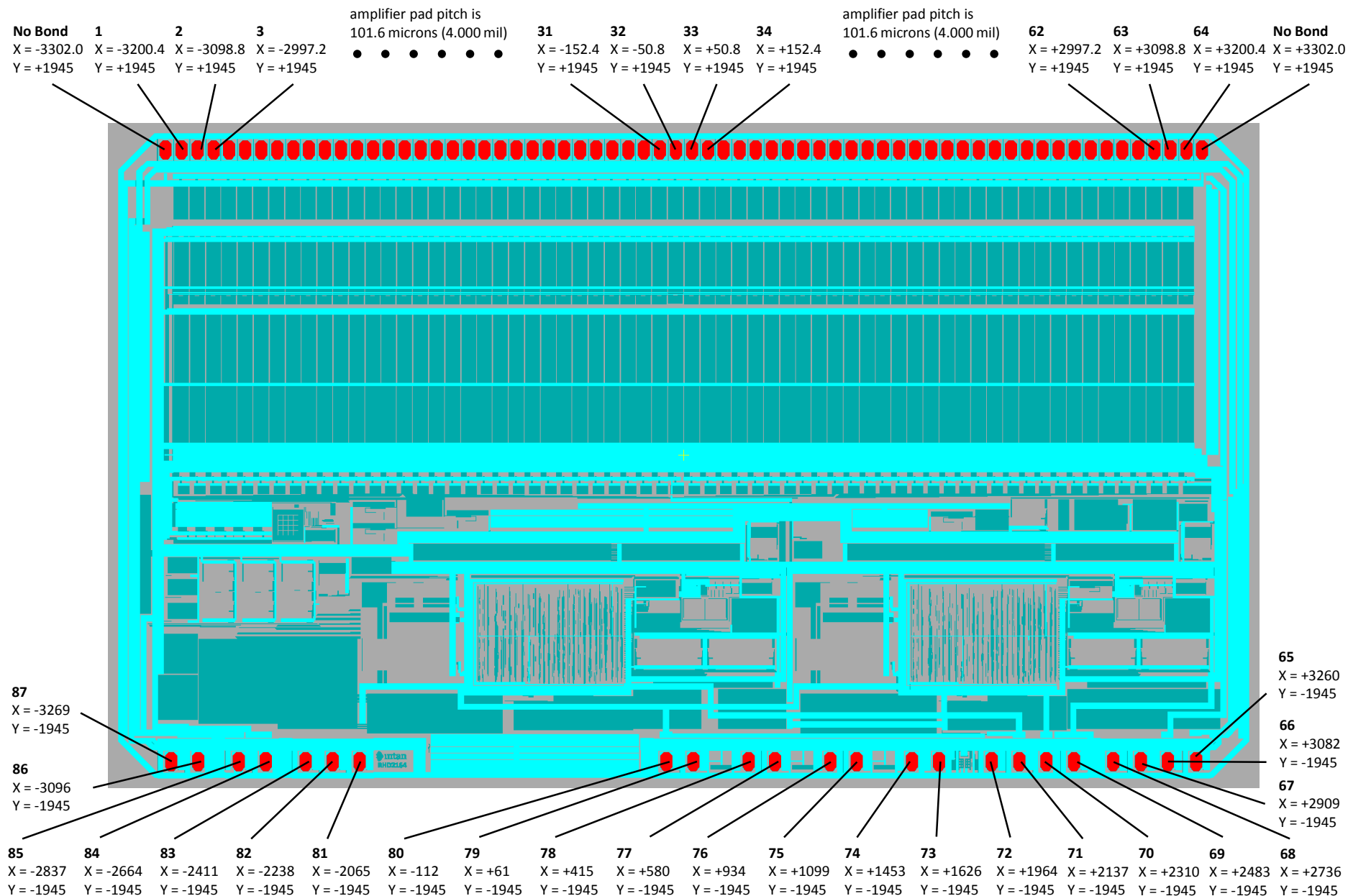
dimensions in microns



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Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns

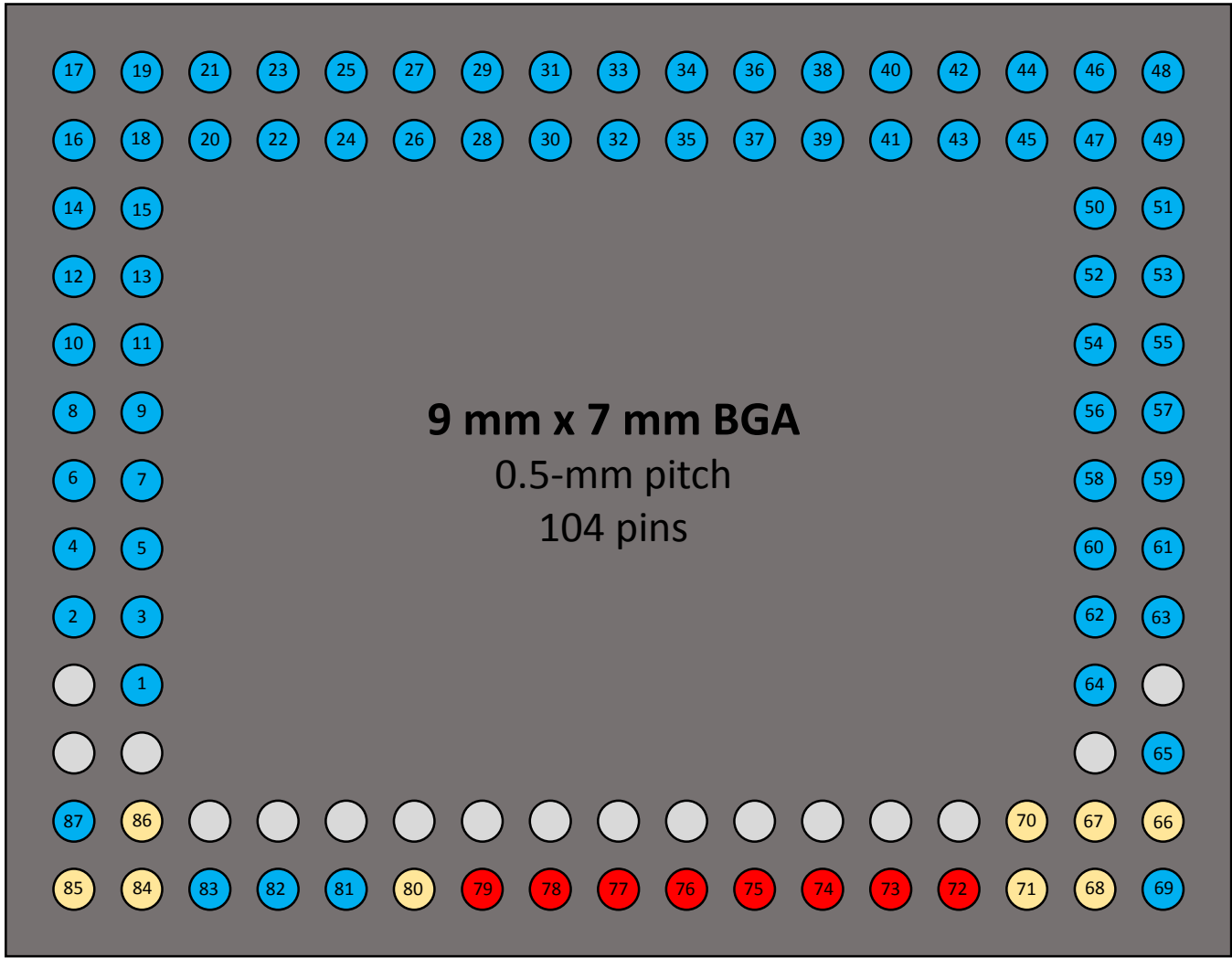


top view (with balls facing **down**)

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-  Red, blue, and yellow pins should connect to **specific bond pads** on the die, as indicated by the number.
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-  Gray pins are not connected.
-  Red pins carry **noisy** signals.
-  Blue pins carry **sensitive** signals.
-  Yellow pins carry signals that are neither noisy nor sensitive.

Noisy signals should not be routed over, under, or near **sensitive signals**.



BACK VIEW

